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FORM **PTO-1595** Rec
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OMD No. 0651-0011 (exp. 6/30/2005)

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To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
Rajashree Baskaran; Shriram Ramanathan; Patrick R. Morrow

Additional name(s) of conveying party(ies) attached? ☒ No ☐ Yes

2. Name and address of receiving party(ies):
Name: **Intel Corporation**
Internal Address:
Street Address: **2200 Mission College Boulevard**
City: **Santa Clara** State: **CA** Zip: **95052**
Country: **United States**
Additional name(s)& address(es) attached? ☒ No ☐ Yes

3. Nature of Conveyance:
☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: 10/20/2005

4. Application number(s) or patent number(s): ☒ This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☒ No ☐ Yes

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: Blakely, Sokoloff, Taylor & Zafman LLP
Internal Address:
Street Address: 12400 Wilshire Boulevard
7th Floor
City: Los Angeles State: CA ZIP: 90025

6. Total number of applications and patents involved: 1

7. Total Fee (37 CFR 3.41)......$ 40.00
☒ Enclosed
☐ Authorized to be charged to deposit account

8. Deposit Account Number:
02-2666
(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.
To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document

Blayne D. Green Blayne D. Green October 24, 2005
Name of Person Signing Signature Date

Total number of pages including cover sheet, attachments, and document: 3

Mail documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services
Director of the US Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450

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Docket No. 42P22132

37 CFR §3.21

Attorney Docket # P22132

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, I (we), the undersigned inventor(s), hereby sell, assign, and transfer to Intel Corporation, a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95052, ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements that are disclosed in the application for the United States patent entitled:

STACKED WAFER OR DIE PACKAGING WITH ENHANCED THERMAL AND DEVICE PERFORMANCE

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original patents, reissued patents, reexamination certificates, and extensions, that have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application;

agree that said Assignee may apply for and receive a patent or patents for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and representatives all facts known to the undersigned relating to said improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or representatives in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Note to each inventor:
On the line below, please enter the date on which you signed the accompanying "Declaration and Power of Attorney":

Rajashree Baskaran	Oct 20, 2005 **(Today's Date)**	Oct 20, 2005 **(Date of Declaration)**
Shriram Ramanathan	**(Today's Date)**	**(Date of Declaration)**
Patrick R. Morrow	**(Today's Date)**	**(Date of Declaration)**

37 CFR §3.21

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and in and to said application and all divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original patents, reissued patents, reexamination certificates, and extensions, that have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application;

agree that said Assignee may apply for and receive a patent or patents for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and representatives all facts known to the undersigned relating to said improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or representatives in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

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Rajashree Baskaran	**(Today's Date)**	**(Date of Declaration)**
	10/20/05	10/20/05
Shriram Ramanathan	**(Today's Date)**	**(Date of Declaration)**
	10/20/05	10/20/05
Patrick R. Morrow	**(Today's Date)**	**(Date of Declaration)**